/ Absolute Maximum Ratings(Ta=25)

Parameter	N Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	400	V
RMS Voltage	V_{RMS}	280	V
DC Blocking Voltage	V_{DC}	400	V
Average Forward Current	I_F	2 × 8	A
Non Repetitive Peak Surge Current	I_{FSM}	120	A
Thermal Resistance Junction to Case	R_{Jc}	2.8	/W
Operating and Storage Temperature Range	T_j T_{stg}	-55 150	

/ Electrical Characteristics(Ta=25)

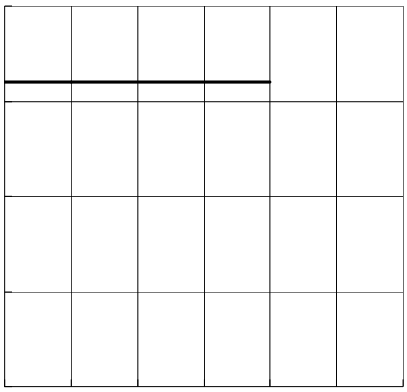
Parameter	N Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	I_F=2A Tc=25		0.93	1.1	V
		I_F=2A Tc=150		0.69	0.8	V
		I_F=8A Tc=25		1.1	1.3	V
		I_F=8A Tc=150		0.92	1.1	V
Instantaneous Reverse Current	I_R Note 1	V_R=400V Ta=25			1.0	A
		V_R=400V Ta=150			100	A
Reverse Recovery Time	t_{rr}	I_F=0.5A, I_R=1.0A, I_{RR}=0.25A			50	ns

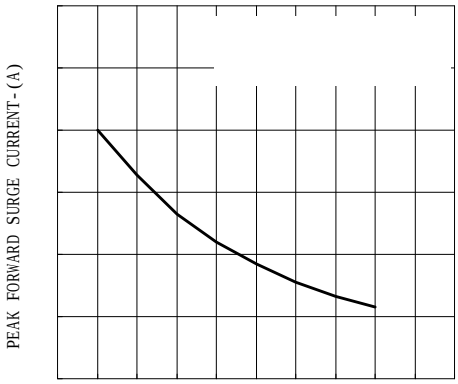
/Notes

41 ڑ ۽ /Short duration pulse test used to minimize self-heating effect.

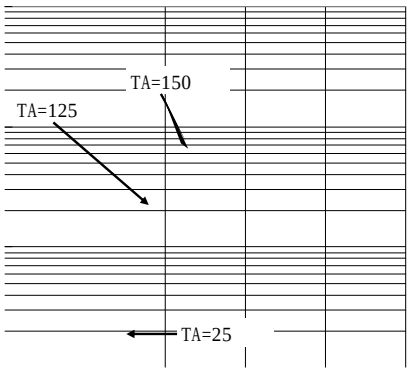
2. ٹ ً / Unless otherwise noted, values for the parameters of a single chip

/ Electrical Characteristic Curve



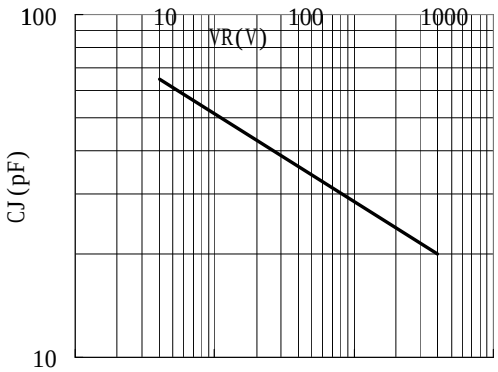


IF - VF

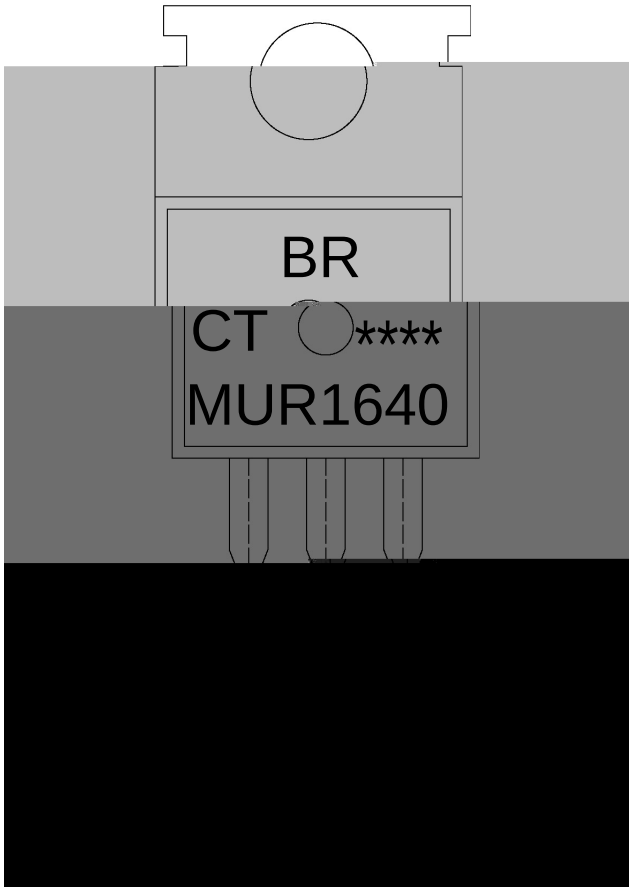


IR - VR





/ Marking Instructions

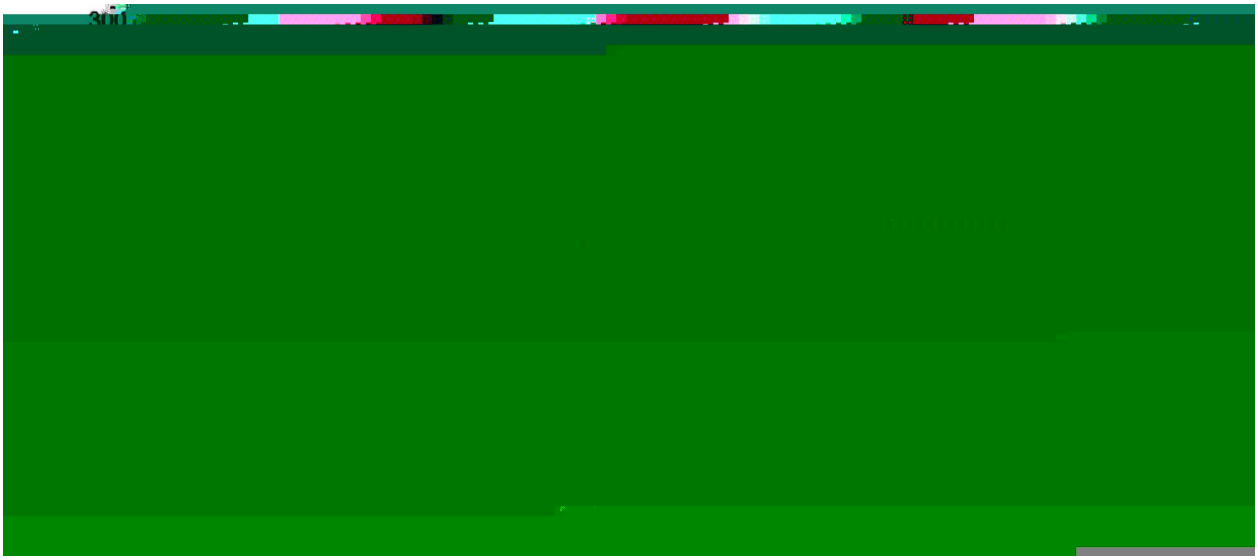


BR	
MXR4643	
CW:	
****	

Note:

BR:	Company Code
MXR4643	Product Type.
CW:	Internal Structure
****:	Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



ب

1 أ 25 150 ژ 60 90sec;

2 255±5 ژ 5±0.5sec;

3 ه 2 10 /sec.

Note:

1.Preheating:25~150 , Time:60~90sec.

2.Peak Temp.:255±5 , Duration:5±0.5sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5 ژ 10±1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units					Dimension		(unit mm³)
	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Bag	Inner Box	Outer Box
TO-220/F	200	10	2,000	5	10,000	135×190	237×172×102	560×245×195

/ TUBE

Package Type	Units					Dimension		(unit mm³)
	Units/Tube /	Tubes/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Tube	Inner Box	Outer Box
TO-220/F	50	20	1,000	5	5,000	532×31.4×5.5	555×164×50	575×290×180

/ Notices